

ASC400N1200HPDL

1200V, 400A, 4mΩ, Six-pack (Three-phase), Silicon Carbide MOSFET Module

Product Data Sheet

ASTC-3T03-173A A/0



爱仕特科技
AST TECHNOLOGY

General Description

The AST-HPD module incorporates AST's 1200V Gen3 N-channel SiC MOSFET. NTC temperature sensor inside.

Features

- High Temperature, Humidity, and Bias Operation
- Ultra Low Loss <10nH
- High-frequency Operation
- Zero Turn-off Tail Current from MOSFET
- Normally-off, Fail-safe Device Operation
- Copper Baseplate and Silicon Nitride Insulator

Benefits

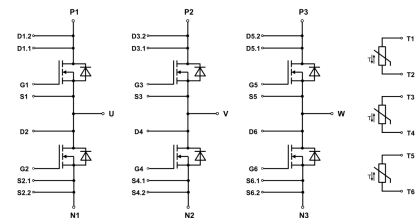
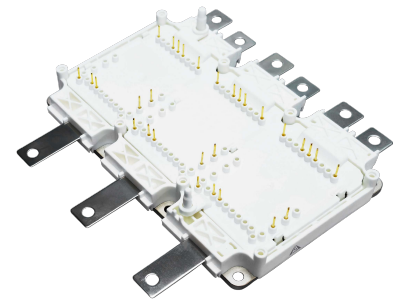
- Enables Compact, Lightweight, Efficient Systems
- Harsh Outdoor Environment Installation
- Mitigates Over-voltage Protection
- Reduced Thermal Requirements and System Cost

Applications

- New Energy Vehicle Main Drive Inverter
- Aviation Controller
- Industrial Controller

Key Parameters

Symbol	Parameter	Values			Unit	Test Conditions
Absolute maximum rating						
V _{DS}	Drain-source Voltage	1200			V	T _c =25°C
I _D	Drain Current (continuous)	400			A	T _c =25°C
T _J	Junction Temperature	175			°C	
Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
Static characteristics						
R _{DS(on)}	Static Drain-source on Resistance	-	4.0	5.5	mΩ	V _{GS} =18V; I _D =200A; T _c =25°C
Dynamic characteristics						
Q _G	Total Gate Charge	-	952	-	nC	V _{DD} =800V; V _{GS} =-5/+18V; I _D =200A; T _c =25°C
Q _{GD}	Gate-drain Charge	-	313	-		
Source-drain diode						
Q _{RR}	Reverse Recovery Charge	-	2452	-	nC	V _{GS} =-5V; I _F =200A; V _R =800V; Load=35μH; R _{G(off)} =5Ω; T _J =25°C



Ordering Informations

Order Number	ASC400N1200HPDL
Marking	ASC400N1200HPDL
Package Type	HPDL

Absolute Maximum Ratings (at $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source Voltage	1200	V
V_{GS}	Gate-source Voltage (dynamic)	-10/+22	V
I_D	Drain Current (continuous)	400	A
I_{DM}	Drain Current (pulsed)	800	A
T_{op}, T_{stg}	Operating and Storage Temperature Range	-40 to +175	$^\circ\text{C}$
T_J	Junction Temperature	175	$^\circ\text{C}$
L_{stray}	Stray Inductance	8.5	nH
V_{isol}	Isolation Test Voltage (DC; 2mA; $t=10\text{s}$)	4.2	kV
$R_{th JC}$	Thermal Resistance, Junction to Cooling Fluid	0.085	$^\circ\text{C/W}$
M	Mounting Torque for Module Mounting (Screw M4 baseplate to heatsink)	2.0	Nm

MOSFET Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
Static characteristics (at $T_c=25^\circ\text{C}$ unless otherwise specified)						
BV_{DS}	Drain-source Breakdown Voltage	1200	-	-	V	$V_{GS}=0\text{V}$
I_{DSS}	Zero Gate Voltage Drain Current	-	-	200	μA	$V_{DS}=1200\text{V}; V_{GS}=0\text{V}$
I_{GSS}	Gate-body Leakage Current	-	-	2.00	μA	$V_{GS}=-10/+20\text{V}; V_{DS}=0\text{V}$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	-	4.0	V	$V_{DS}=V_{GS}; I_D=40\text{mA}$
$R_{DS(on)}$	Static Drain-source on Resistance	-	4.0	5.5	$\text{m}\Omega$	$V_{GS}=18\text{V}; I_D=200\text{A}$
$V_{GS(on)}$	Recommended Turn-on Voltage	-	18	-	V	Static
$V_{GS(off)}$	Recommended Turn-off Voltage	-	-5	-	V	
R_G	Gate Resistance	-	0.55	-	Ω	$V_{AC}=25\text{mV}; f=1\text{MHz}$
Dynamic characteristics (at $T_c=25^\circ\text{C}$ unless otherwise specified)						
C_{iss}	Input Capacitance	-	27.5	-	nF	$V_{DS}=1000\text{V}; f=1\text{MHz}; V_{AC}=25\text{mV}$
C_{oss}	Output Capacitance	-	1.15	-		
C_{rss}	Reverse Transfer Capacitance	-	52	-	pF	
E_{on}	Turn-on Switching Energy	-	15.0	-	mJ	$V_{DD}=800\text{V}; V_{GS}=-5/+18\text{V}; I_D=200\text{A}; R_{G(ext)}=5.0\Omega; \text{Load}=35\mu\text{H}$
E_{off}	Turn-off Switching Energy	-	5.2	-		
Q_{GS}	Gate-source Charge	-	307	-	nC	$V_{DD}=800\text{V}; V_{GS}=-5/+18\text{V}; I_D=200\text{A}$
Q_{GD}	Gate-drain Charge	-	313	-		
Q_G	Total Gate Charge	-	952	-		
$t_{d(on)}$	Turn-on Delay Time	-	94	-	ns	$V_{DD}=800\text{V}; V_{GS}=-5/+18\text{V}; I_D=200\text{A}; R_{G(ext)}=5.0\Omega; \text{Load}=35\mu\text{H}$
t_r	Rise Time	-	46	-		
$t_{d(off)}$	Turn-off Delay Time	-	294	-		
t_f	Fall Time	-	42	-		

Body Diode Characteristics (at $T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
V_{FSD}	Forward Voltage	-	3.6	6	V	$V_{GS}=0\text{V}$; $I_F=200\text{A}$
I_S	Continuous Diode Forward Current	-	200	-	A	$V_{GS}=0\text{V}$; $T_C=25^{\circ}\text{C}$
t_{RR}	Reverse Recovery Time	-	53	-	ns	$V_{GS}=-5\text{V}$; $I_F=200\text{A}$; $V_R=800\text{V}$; $R_{G(off)}=5\Omega$; Load=35 μH
Q_{RR}	Reverse Recovery Charge	-	2452	-	nC	
I_{RRM}	Peak Reverse Recovery Current	-	152	-	A	

NTC Thermistor Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
R_{25}	Rated Resistance	-	5.00	-	k Ω	$T_{NTC}=25^{\circ}\text{C}$
$\Delta R/R$	Deviation of R_{100}	-5	-	5	%	$T_{NTC}=100^{\circ}\text{C}$; $R_{100}=493.3\Omega$
$B_{25/50}$	Beta Value for 25°C to 50°C	-	3375	-	K	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$
$B_{25/80}$	Beta Value for 25°C to 80°C	-	3414	-	K	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$
$B_{25/100}$	Beta Value for 25°C to 100°C	-	3436	-	K	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$

Typical Performance

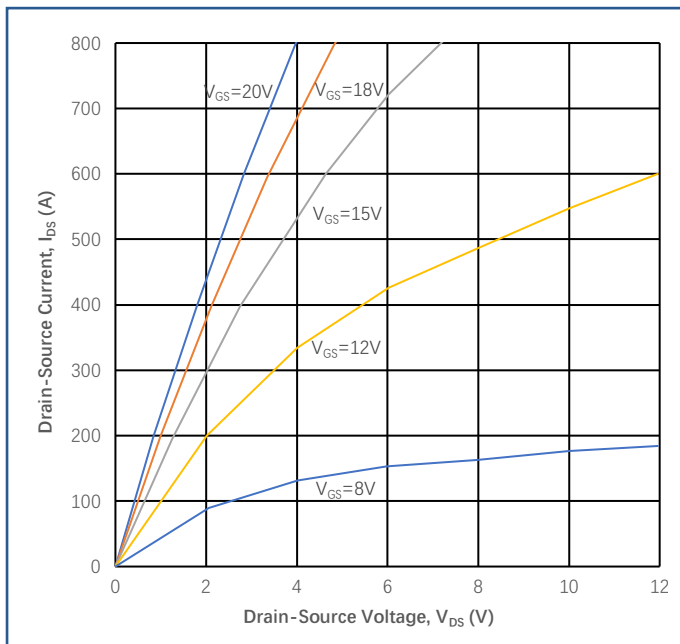


Figure 1
Output Characteristics (T_J=25°C)

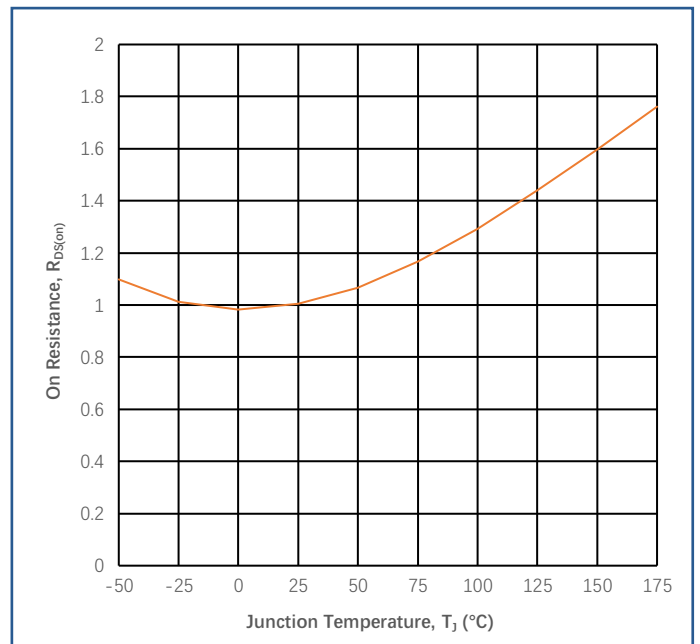


Figure 2
Normalized On-Resistance vs. Temperature

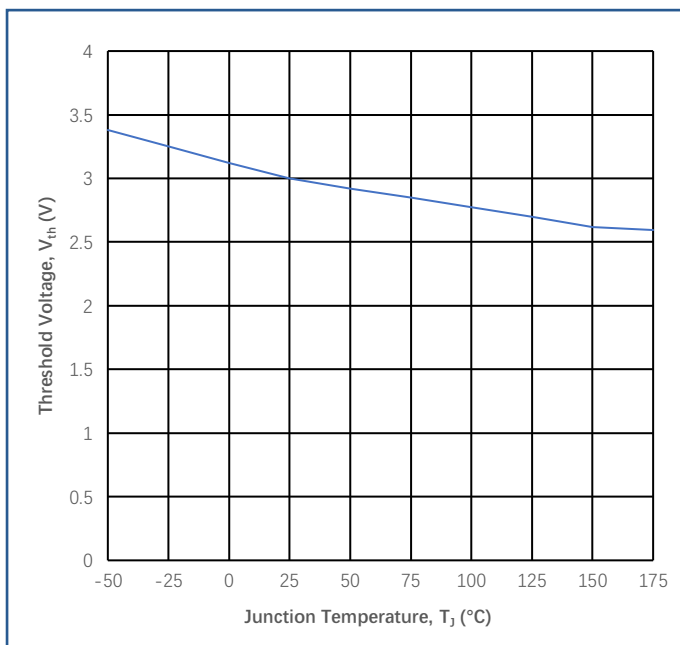


Figure 3
Threshold Voltage vs. Temperature

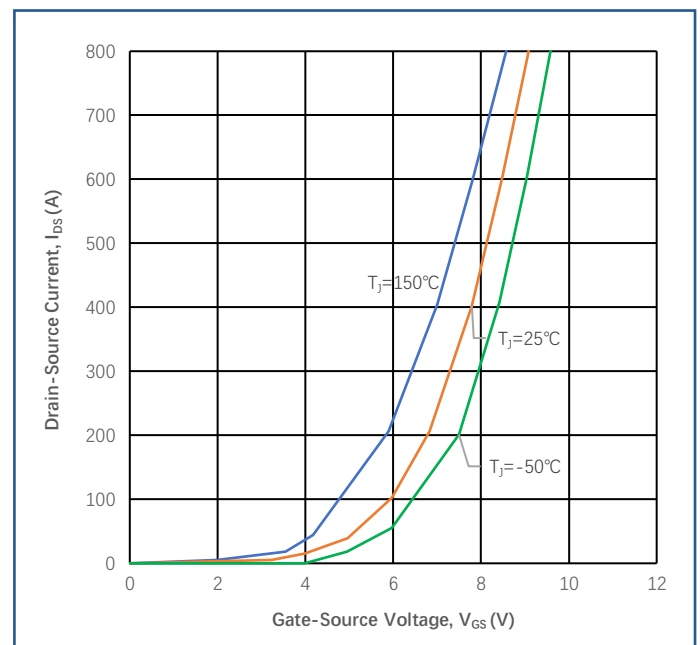


Figure 4
Transfer Characteristic for Various T_J

Typical Performance

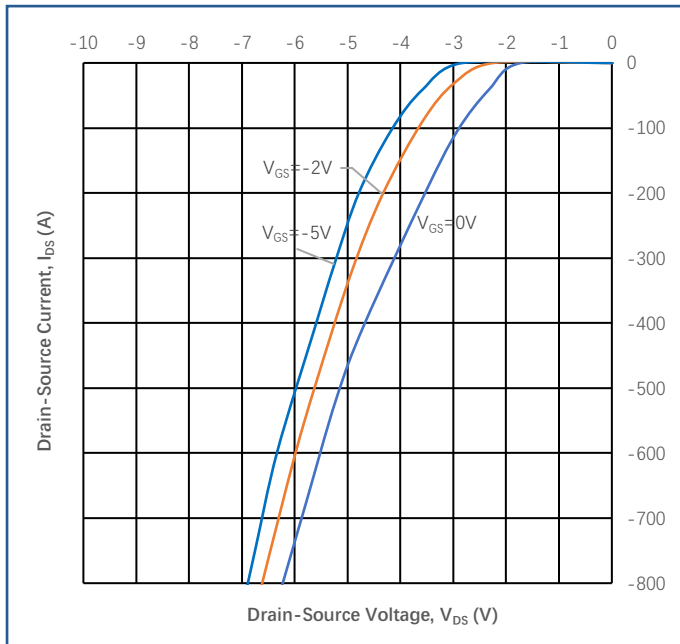


Figure 5
Diode Characteristic at 25°C

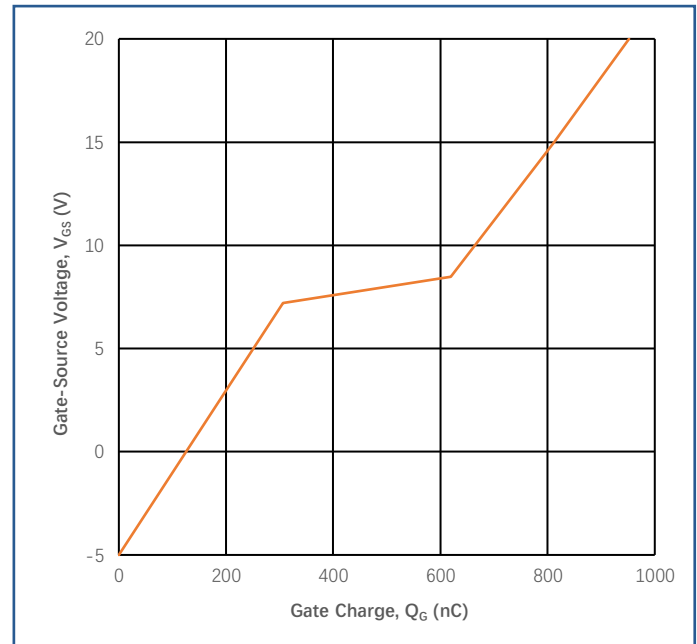


Figure 6
Typical Gate Charge Characteristics

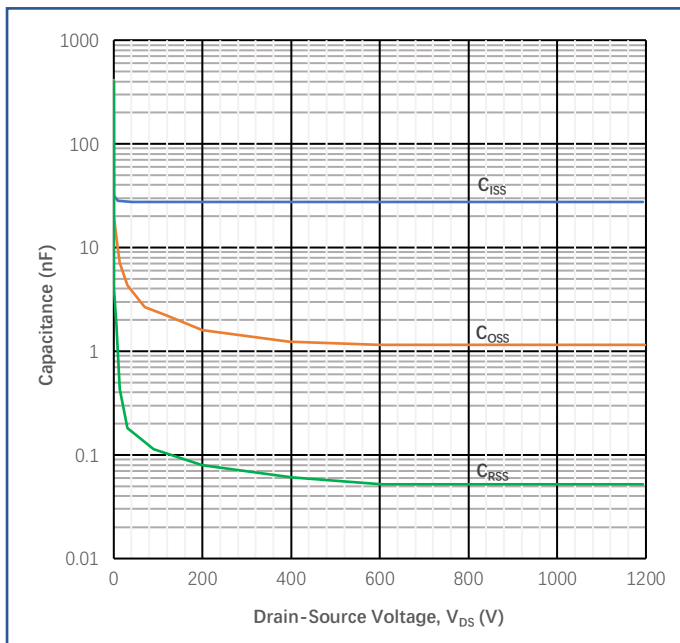


Figure 7
Typical Capacitances vs. Drain-Source Voltage

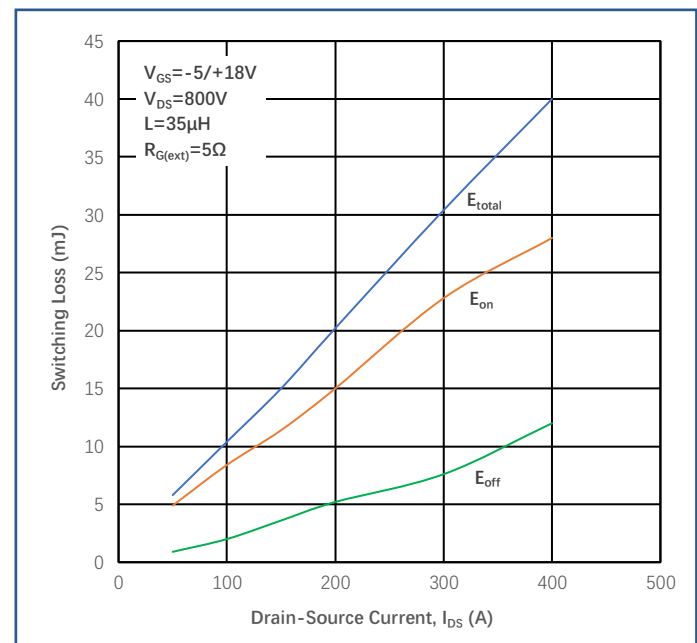


Figure 8
Inductive Switching Energy vs. Drain Current

Typical Performance

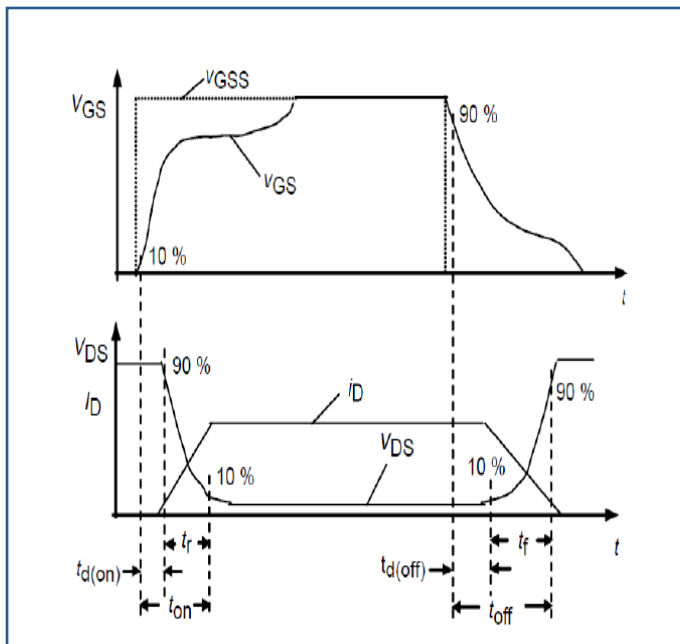


Figure 9
Switching Time Description

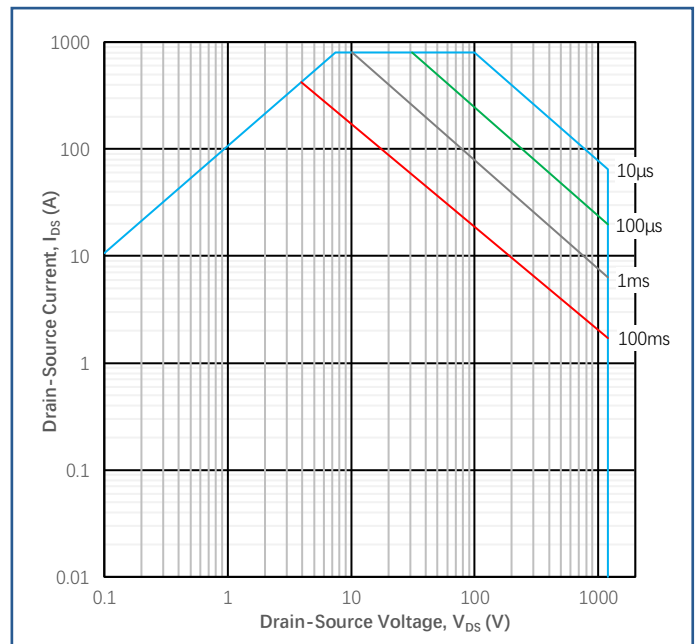
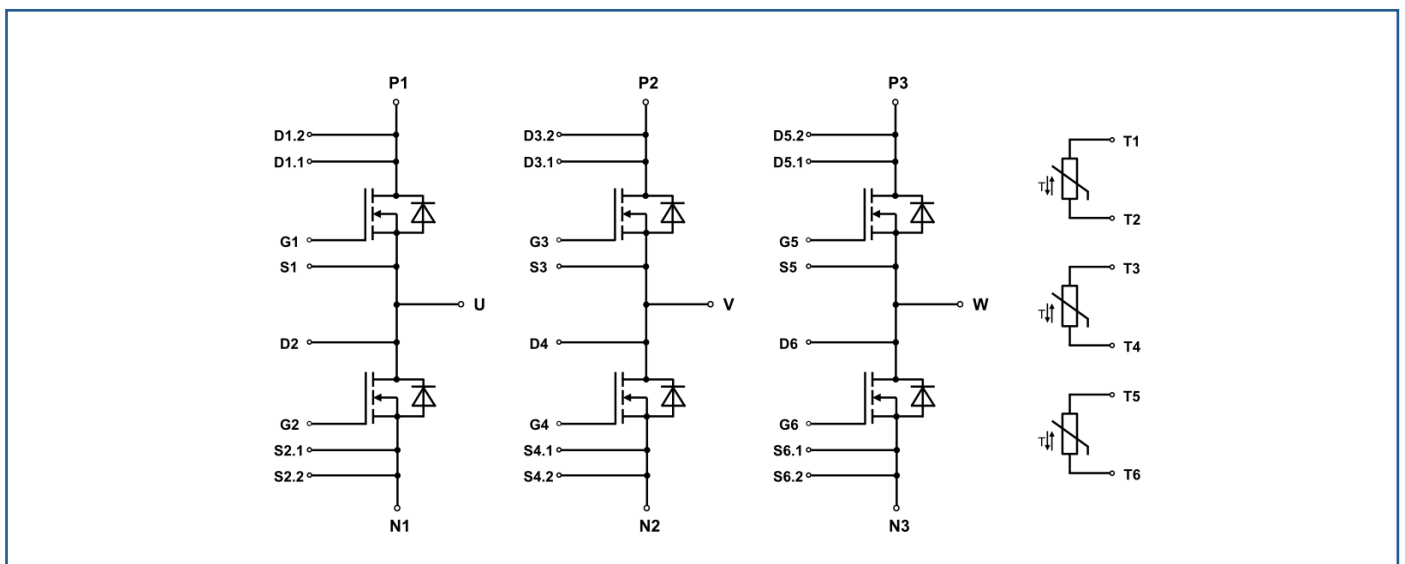


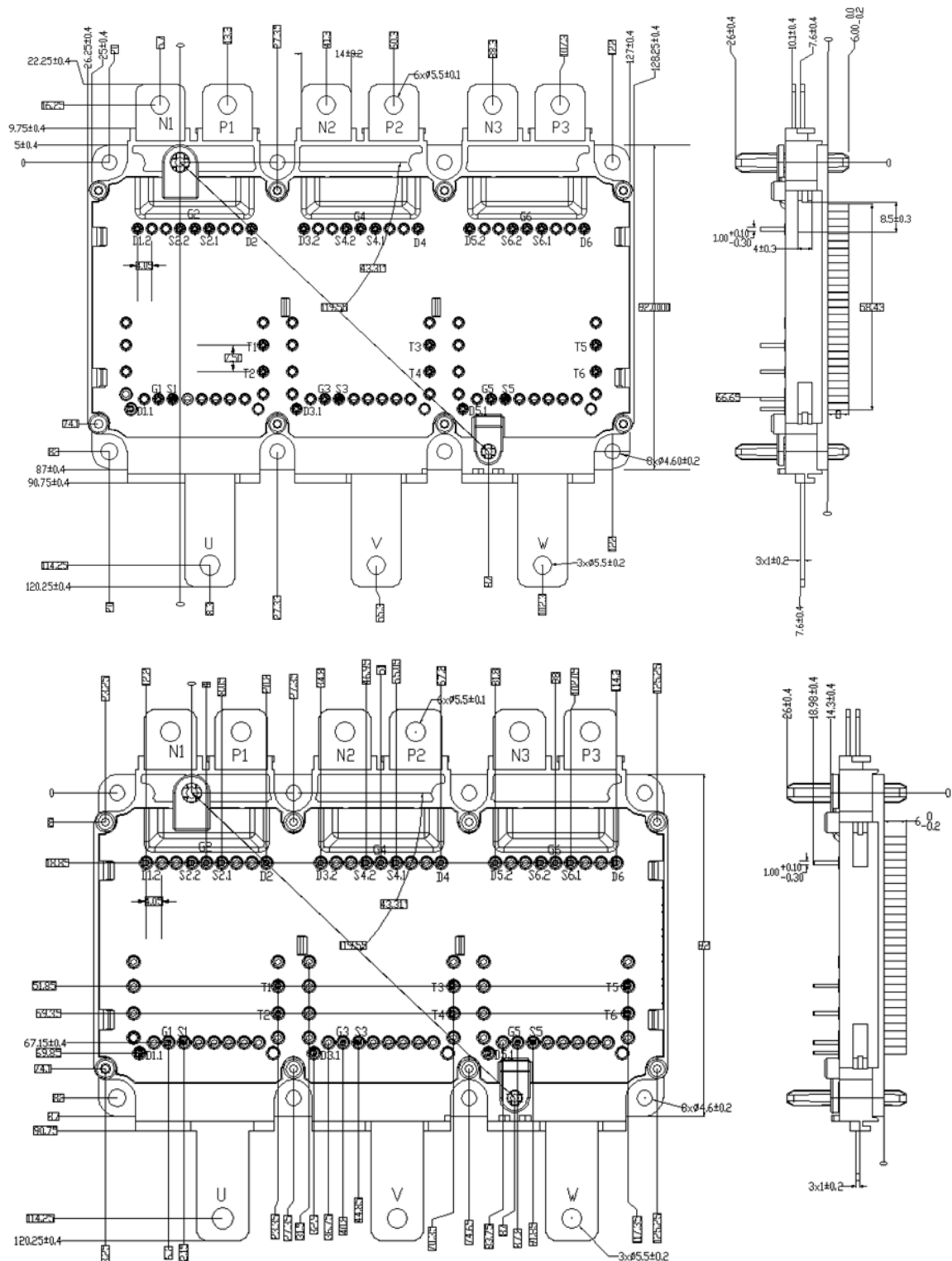
Figure 10
Safe Operating Area

Circuit Diagram Headline



Package Dimensions (mm)

Package Type: HPDL



未标注线性公差按 GB/1804-2000c 级执行	公差分段	0.5-3	3-6	6-30	30-120	120-400
	c 级	±0.2	±0.3	±0.5	±0.8	±1.2

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